

**Claim Amendments**

1. (Currently Amended) A method for making a microfluidic structure, at least a portion of which is intermetallic, by a microlamination process, the method comprising:  
forming a ductile, patternable intermetallic foil by roll compaction of metal powders;  
patternning at least one the patternable intermetallic lamina to form a NON-CORRUGATED patterned intermetallic lamina, the patternable intermetallic lamina comprising nickel aluminide, iron aluminide or titanium aluminide, wherein patterning is selected from lithography, laser ablation, an electrochemical machining process, chemical etching, plasma etching, mechanical cutting, a hydraulic process, solid abrasion, particle beam, ultrasonic machining, electromagnetic machining, wire and ram electrodischarge (EDM), waterjet, abrasive waterjet, precision plasma cutting, or combinations thereof;  
adding at least one bonding material to the registered stack to facilitate bonding between the intermetallic lamina and a second lamina adjacent the intermetallic lamina;  
stacking and registering the patterned intermetallic lamina with at least one lamina other than the bonding lamina selected from patterned lamina, non-patterned lamina and combinations thereof, thereby forming a registered stack; and  
processing the registered stack to make a microfluidic structure comprising an intermetallic structure.

Claim 2 (Canceled).

3. (Previously Presented) The method according to claim 1 where the nickel aluminide is NiAl.

4. (Previously Presented) The method according to claim 1 where the nickel aluminide is Ni<sub>3</sub>Al.

Claim 5 (Canceled).

6. (Previously Presented) The method according to claim 1 where the iron aluminide is FeAl.

7. (Previously Presented) The method according to claim 1 where the iron aluminide is Fe<sub>3</sub>Al.

Claim 8 (Canceled).

9. (Previously Presented) The method according to claim 1 where the titanium aluminide is TiAl.

10. (Previously Presented) The method according to claim 1 where the titanium aluminide is Ti<sub>3</sub>Al.

11. (Previously Presented) The method according to claim 1 where the bonding material is positioned between a first intermetallic lamina and a second intermetallic lamina.

12. (Previously Presented) The method according to claim 11 where the bonding material is substantially pure nickel.

13. (Previously Presented) The method according to claim 12 where the bonding material has a thickness of from about 5 to about 10 microns.

Claim 14 (Canceled).

15. (Previously Presented) The method according to claim 1 comprising procuring a patterned lamina or lamina blank.

16. (Previously Presented) The method according to claim 1 further comprising providing at least a second lamina in addition to the at least one patternable intermetallic lamina, the second lamina comprising at least a first metal layer and a second metal layer.

17. (Previously Presented) The method according to claim 16 where each of the first and second metal layers comprises a substantially pure metal prior to heat treatment.

18. (Original) The method according to claim 17 where the second lamina comprises three metal layers.

19. (Original) The method according to claim 18 where one of the layers comprises an element different from the other two layers.

20. (Previously Presented) The method according to claim 19 where one of the layers is substantially pure iron, nickel, titanium or aluminum.

21. (Original) The method according to claim 18 wherein two of the layers are substantially pure aluminum, and one layer is substantially pure nickel.

22. (Original) The method according to claim 18 where two of the layers are substantially pure aluminum, and one layer is substantially pure titanium.

23. (Previously Presented) The method according to claim 1 further comprising applying an adhesive between two or more laminae.

24. (Original) The method according to claim 17 where processing comprises vacuum heating at a temperature and for a length of time sufficient to form an intermetallic.

25. (Original) The method according to claim 16 where processing further comprises liquid-phase bonding.

26. (Original) The method according to claim 16 where processing further comprises diffusion bonding.

27. (Original) The method according to claim 1 wherein the intermetallic structure includes one or more catalysts operatively associated therewith.

Claims 28-36 (Canceled).

37. (Previously Presented) The method according to claim 1 where at least two adjacent lamina are connected by at least one post.

Claims 38-42 (Canceled).

43. (Previously Presented) The method according to claim 1 where at least one lamina in the registered stack comprises a metal selected from aluminum, nickel, titanium, molybdenum, tantalum, copper, gold, silver, lead, tin, iron, antimony, magnesium, manganese, bismuth, germanium, tungsten, binary alloys thereof, binary intermetallics thereof, ternary alloys thereof, ternary intermetallics thereof, and combinations thereof.

44. (Original) The method according to claim 43 where the metal is a metal foil.

45. (Previously Presented) The method according to claim 1 where the registered stack comprises plural intermetallic foils.

46. (Previously Presented) The method according to claim 16 further comprising ordering metal layers in a predetermined order selected to minimize voids during heat processing that result from Kirkendall porosities.

Claim 47 (Canceled).